

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

RAILE
Application Serial No
Filing Date December 16, 1999
Inventor Segal et al.
Assignee
Group Art Unit
Examiner Wilkins, III
Attorney's Docket No
Title: Snuttering Targets Formed From Cast Materials

Sputtering Targets Formed From Cast Materials

INFORMATION DISCLOSURE STATEMENT

References -- See Attached Form PTO-1449

The Examiner's attention is directed to the references which are listed on the attached Form PTO-1449, copies of which are attached. No admission is made regarding whether all the submitted references are prior art.

Citation of the referenced art is respectfully requested.

Respectfully submitted,

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U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE

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ATTY. DOCKET NO. 30-5004(4015)

SERIAL NO. 09/465,492

LIST OF ART CITED BY APPLICANT
(Use several sheets if necessary)

APPLICANT Vladimir Segal et al.

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	AR		Susumu Sawada, "On Advanced Sputtering Targets of Refractory Metals and Their Silicides for VLSI-Applications", 12th International Plansee Seminar (1989) Topic 5: Ultrapure Refractory Metals, pp. 201-222.										
	AS		P. Ding et al., "Copper Barrier, Seed Layer, and Planarization Technologies", June 10-12, 1997 VMIC Conference, pp. 87-92.										
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EXAMINER DATE CONSIDERED													

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered.

Include copy of this form with next communication to applicant.